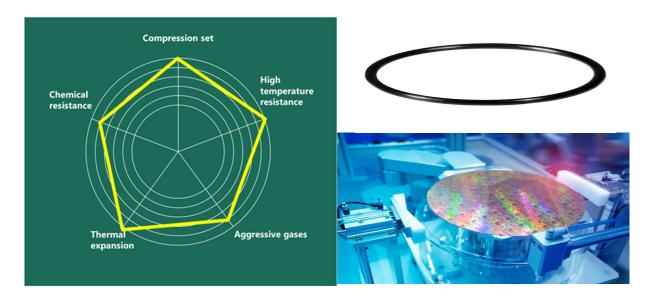


## SEALR&Z 4175SC

## for thermal semiconductor processes

Sealrez compounds for semiconductor processes are developed to manufacture high quality O-rings and custom moulded parts including bonded gates. Ultraclean manufacturing takes place in ISO class 7 cleanrooms, whereas cleaning and packaging takes place in ISO class 5 cleanrooms.

Sealrez® 4175SC perfluorelastomer compounds in black color have been developed for harsh chemical and high temperature semiconductor processes. Sealrez® 4175SC compounds excel in thermal processes with low thermal expansion and low compression set.



Physical Properties	Unit	Measured
Hardness <sup>1</sup>	Shore-A	73
Tensile strength <sup>2</sup>	MPa (psi)	15,1 (2184)
Elongation at break <sup>2</sup>	%	150
Modulus @ 100% <sup>2</sup>	MPa (psi)	5,70 (827)
Compression set 70hrs @ 300°C <sup>3</sup>	%	32,5
Minimum operating temperature	°C	-15
Maximum operating temperature	°C	300

<sup>&</sup>lt;sup>1</sup> ASTM D2240

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<sup>&</sup>lt;sup>2</sup> ASTM D1414

<sup>3</sup> ASTM D395B